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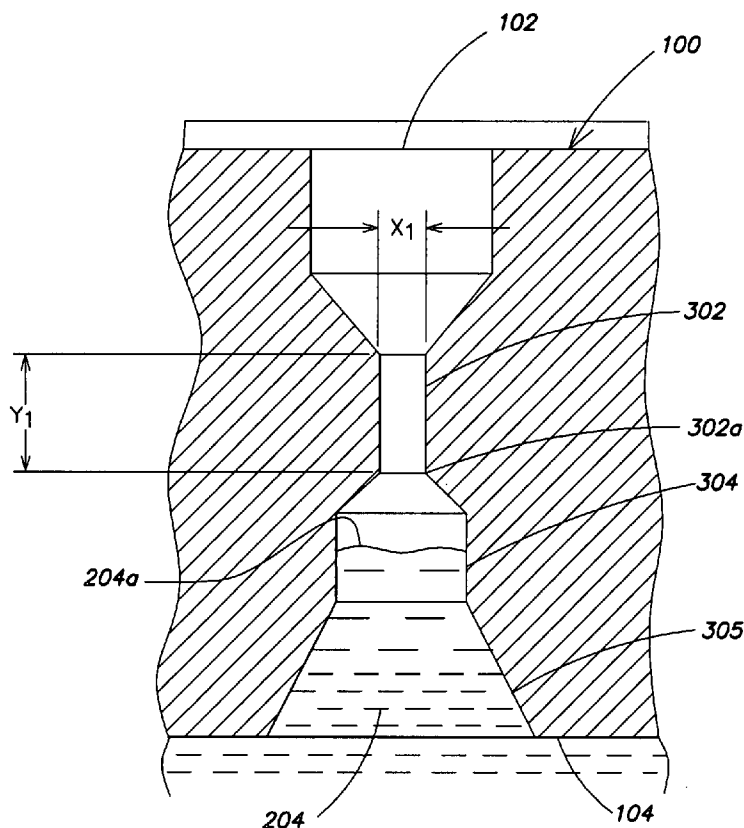
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(54) Title: METHODS AND APPARATUS FOR CLEANING CHAMBER COMPONENTS



(57) Abstract: In a first aspect, a method for cleaning a semiconductor fabrication chamber component having an orifice is provided. The method includes (A) placing the component into a bath having a cleaning solution; (B) flowing a fluid into the orifice thereby maintaining at least a first portion of the orifice free from cleaning solution while the cleaning solution cleans the component; and (C) withdrawing the fluid from the orifice such that cleaning solution enters into the first portion of the orifice and cleans the first portion of the orifice. Numerous other aspects are also provided.



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